

IRF7807PbF IRF7807APbF

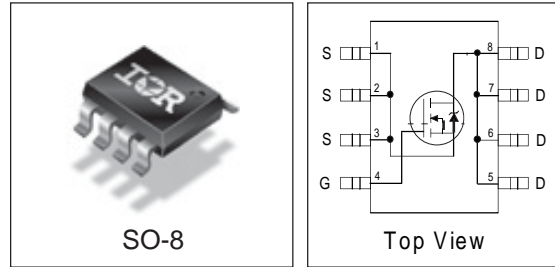
HEXFET® Chip-Set for DC-DC Converters

- N Channel Application Specific MOSFETs
- Ideal for Mobile DC-DC Converters
- Low Conduction Losses
- Low Switching Losses
- Lead-Free

Description

These new devices employ advanced HEXFET Power MOSFET technology to achieve an unprecedented balance of on-resistance and gate charge. The reduced conduction and switching losses make them ideal for high efficiency DC-DC Converters that power the latest generation of mobile microprocessors.

A pair of IRF7807 devices provides the best cost/performance solution for system voltages, such as 3.3V and 5V.



Device Features

	IRF7807	IRF7807A
V _{ds}	30V	30V
R _{ds(on)}	25mΩ	25mΩ
Q _g	17nC	17nC
Q _{sw}	5.2nC	
Q _{oss}	16.8nC	16.8nC

Absolute Maximum Ratings

Parameter	Symbol	IRF7807	IRF7807A	Units	
Drain-Source Voltage	V _{DS}	30		V	
Gate-Source Voltage	V _{GS}	±12			
Continuous Drain or Source Current (V _{GS} ≥ 4.5V)	I _D	25°C	8.3	A	
		70°C	6.6		
Pulsed Drain Current ^①	I _{DM}	66	66		
Power Dissipation	P _D	25°C	2.5		W
		70°C	1.6		
Junction & Storage Temperature Range	T _J , T _{STG}	-55 to 150		°C	
Continuous Source Current (Body Diode) ^②	I _S	2.5	2.5	A	
Pulsed source Current	I _{SM}	66	66		

Thermal Resistance

Parameter	Symbol	Max.	Units
Maximum Junction-to-Ambient ^③	R _{θJA}	50	°C/W

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Electrical Characteristics

Parameter		IRF7807			IRF7807A			Units	Conditions
		Min	Typ	Max	Min	Typ	Max		
Drain-to-Source Breakdown Voltage*	$V_{(BR)DSS}$	30	-	-	30	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Static Drain-Source on Resistance*	$R_{DS(on)}$		17	25		17	25	m Ω	$V_{GS} = 4.5V, I_D = 7A$ Ⓜ
Gate Threshold Voltage*	$V_{GS(th)}$	1.0			1.0			V	$V_{DS} = V_{GS}, I_D = 250\mu A$
Drain-Source Leakage Current*	I_{DSS}			30			30	μA	$V_{DS} = 24V, V_{GS} = 0$
				150			150		$V_{DS} = 24V, V_{GS} = 0,$ $T_j = 100^\circ C$
Gate-Source Leakage Current*	I_{GSS}			± 100			± 100	nA	$V_{GS} = \pm 12V$
Total Gate Charge*	Q_g		12	17		12	17	nC	$V_{GS} = 5V, I_D = 7A$
Pre-Vth Gate-Source Charge	Q_{gs1}		2.1			2.1			$V_{DS} = 16V, I_D = 7A$
Post-Vth Gate-Source Charge	Q_{gs2}		0.76			0.76			
Gate to Drain Charge	Q_{gd}		2.9			2.9			
Switch Charge* ($Q_{gs2} + Q_{gd}$)	Q_{SW}		3.66	5.2		3.66			
Output Charge*	Q_{oss}		14	16.8		14	16.8		$V_{DS} = 16V, V_{GS} = 0$
Gate Resistance	R_g		1.2			1.2		Ω	
Turn-on Delay Time	$t_d(on)$		12			12		ns	$V_{DD} = 16V$
Rise Time	t_r		17			17			$I_D = 7A$
Turn-off Delay Time	$t_d(off)$		25			25			$R_g = 2\Omega$
Fall Time	t_f		6			6			$V_{GS} = 4.5V$ Resistive Load

Source-Drain Rating & Characteristics

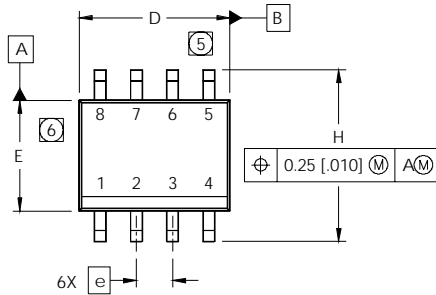
Parameter		Min	Typ	Max	Min	Typ	Max	Units	Conditions
Diode Forward Voltage*	V_{SD}			1.2			1.2	V	$I_S = 7A$ Ⓜ, $V_{GS} = 0V$
Reverse Recovery Charge④	Q_{rr}		80			80		nC	$di/dt = 700A/\mu s$ $V_{DS} = 16V, V_{GS} = 0V, I_S = 7A$
Reverse Recovery Charge (with Parallel Schottky)④	$Q_{rr(s)}$		50			50			$di/dt = 700A/\mu s$ (with 10BQ040) $V_{DS} = 16V, V_{GS} = 0V, I_S = 7A$

Notes:

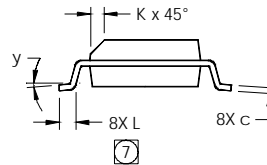
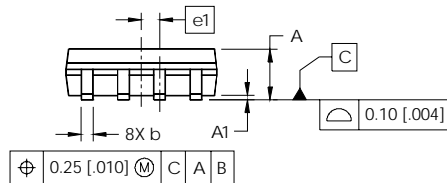
- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width $\leq 300 \mu s$; duty cycle $\leq 2\%$.
- ③ When mounted on 1 inch square copper board, $t < 10$ sec.
- ④ Typ = measured - Q_{oss}
- * Devices are 100% tested to these parameters.

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SO-8 Package Outline

Dimensions are shown in millimeters (inches)



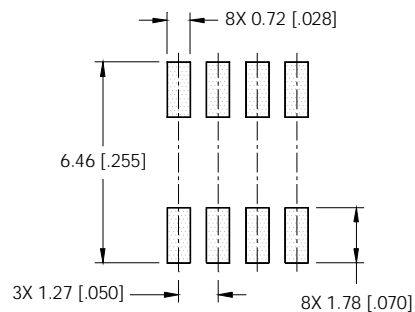
DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
c	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
E	.1497	.1574	3.80	4.00
e	.050 BASIC		1.27 BASIC	
e1	.025 BASIC		0.635 BASIC	
H	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
y	0°	8°	0°	8°



NOTES:

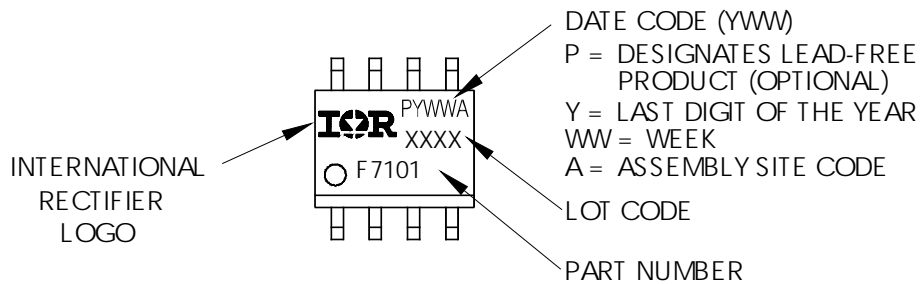
1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: MILLIMETER
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
5. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [0.006].
6. DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [0.010].
7. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.

FOOTPRINT



SO-8 Part Marking

EXAMPLE: THIS IS AN IRF7101 (MOSFET)

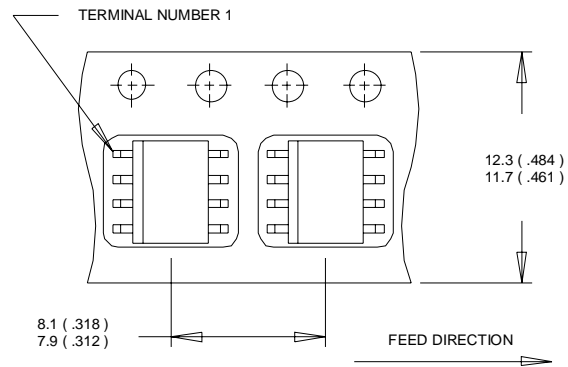


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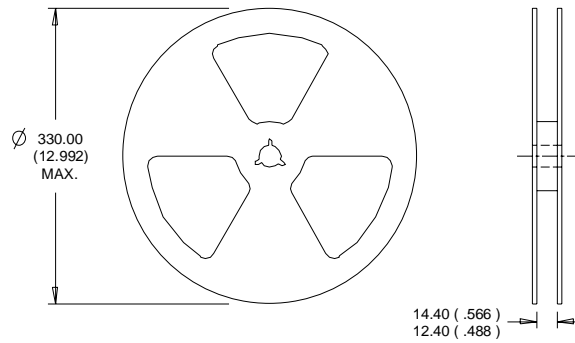
SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



NOTES:

1. CONTROLLING DIMENSION : MILLIMETER.
2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES :

1. CONTROLLING DIMENSION : MILLIMETER.
2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Data and specifications subject to change without notice.
This product has been designed and qualified for the Consumer market.

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